

*1M x 4bit CMOS Quad CAS DRAM with Extended Data Out*

**DESCRIPTION**

This is a family of 1,048,576 x 4bit Extended Data Out Quad CAS CMOS DRAMs. Extended Data Out offers high speed random access of memory cells within the same row. Access time (-5, -6 or -7), power consumption(Normal), and package type (SOJ or TSOP-II) are optional features of this family. All of this family have  $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  refresh,  $\overline{\text{RAS}}$ -only refresh and Hidden refresh capabilities. Furthermore, Self-refresh operation is available in Low power version. Four separate  $\overline{\text{CAS}}$  pins provide for separate I/O operation allowing this device to operate in parity mode. This 1Mx4 Extended Data Out DRAM family is fabricated using Samsung's advanced CMOS process to realize high band-width, low power consumption and high reliability.

**FEATURES**

• **Part Identification**

- KM44C1005D(5V, 1K Ref.)

• **Active Power Dissipation**

Unit : mW

Speed	Active power dissipation
-5	468
-6	413
-7	358

• **Refresh Cycles**

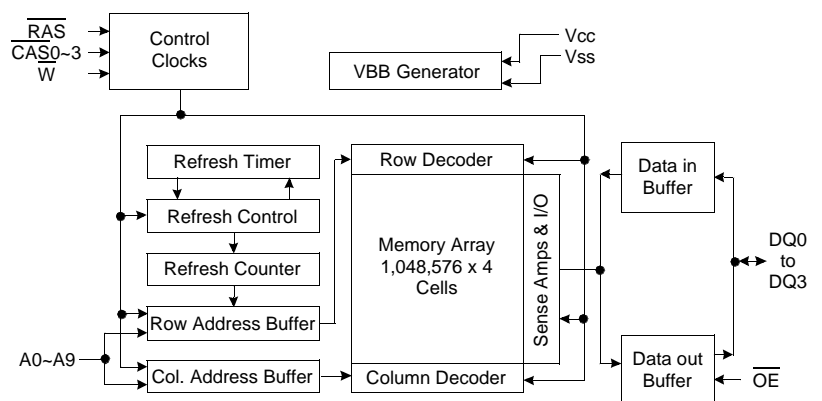
Part NO.	Refresh cycle	Refresh Period
		Normal
KM44C1005D	1K	16ms

• **Performance Range**

Speed	t <sub>RAC</sub>	t <sub>CAC</sub>	t <sub>RC</sub>	t <sub>HPC</sub>
-5	50ns	15ns	84ns	20ns
-6	60ns	15ns	104ns	25ns
-7	70ns	20ns	124ns	30ns

- Extended Data Out mode operation (Fast Page Mode with Extended data out)
- Four separate  $\overline{\text{CAS}}$  pins provide for separate I/O operation
- $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  refresh capability
- $\overline{\text{RAS}}$ -only and Hidden refresh capability
- Self-refresh capability (L-ver only)
- Fast parallel test mode capability
- TTL compatible inputs and outputs
- Early Write or output enable controlled write
- JEDEC Standard pinout
- Available in 26(24)-pin SOJ 300mil and TSOP(II) 300mil packages
- Single +5V±10% power supply

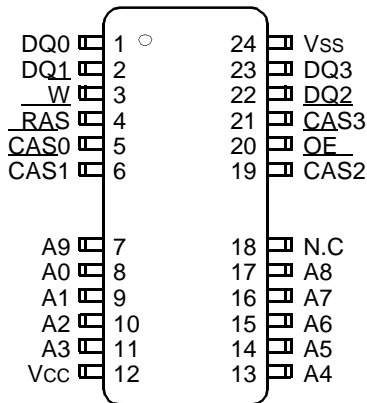
**FUNCTIONAL BLOCK DIAGRAM**



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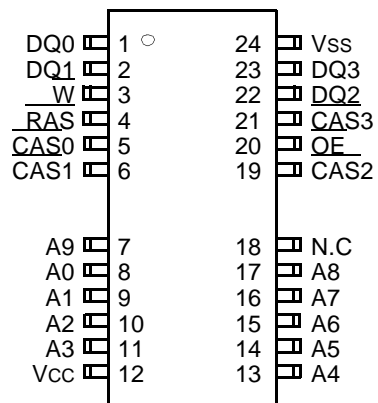
PIN CONFIGURATION (Top Views)

• KM44C1005DJ



( SOJ )

• KM44C1005DT



( TSOP-II )

Pin Name	Pin function
A0 - A9	Address Inputs
DQ0 - 3	Data In/Out
Vss	Ground
$\overline{RAS}$	Row Address Strobe
$\overline{CAS0}$ ~ $\overline{CAS3}$	Column Address Strobe
$\overline{W}$	Read/Write Input
$\overline{OE}$	Data Output Enable
Vcc	Power(+5.0V)
N.C	No Connection

## ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating	Units
Voltage on any pin relative to Vss	V <sub>IN</sub> , V <sub>OUT</sub>	-1 to +7.0	V
Voltage on Vcc supply relative to Vss	V <sub>CC</sub>	-1 to +7.0	V
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C
Power Dissipation	P <sub>D</sub>	1	W
Short Circuit Output Current	I <sub>OS</sub> Address	50	mA

\* Permanent device damage may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## RECOMMENDED OPERATING CONDITIONS (Voltage referenced to Vss, T<sub>A</sub> = 0 to 70°C)

Parameter	Symbol	Rating	Typ	Max	Units
Supply Voltage	V <sub>CC</sub>	4.5	5.0	5.5	V
Ground	V <sub>SS</sub>	0	0	0	V
Input High Voltage	V <sub>IH</sub>	2.4	-	V <sub>CC</sub> +1.0* <sup>1</sup>	V
Input Low Voltage	V <sub>IL</sub>	-1.0* <sup>2</sup>	-	0.8	V

\*1 : V<sub>CC</sub> +2.0V at pulse width ≤ 20ns, Pulse width is measured at V<sub>CC</sub>

\*2 : - 2.0V at pulse width ≤ 20ns, Pulse width is measured at V<sub>SS</sub>

## DC AND OPERATING CHARACTERISTICS (Recommended operating conditions unless otherwise noted.)

Parameter	Symbol	Min	Max	Units
Input Leakage Current (Any input 0 ≤ V <sub>IN</sub> ≤ V <sub>CC</sub> +0.5V, all other input pins not under test = 0 Volt)	I <sub>I(L)</sub>	-5	5	μA
Output Leakage Current (Data out is disabled, 0V ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub> )	I <sub>O(L)</sub>	-5	5	μA
Output High Voltage Level (I <sub>OH</sub> = -5mA)	V <sub>OH</sub>	2.4	-	V
Output Low Voltage Level (I <sub>OL</sub> = 4.2mA)	V <sub>OL</sub>	-	0.4	V

**DC AND OPERATING CHARACTERISTICS** (Continued)

Symbol	Power	Speed	Max	Units
			KM44C1005D	
I <sub>CC1</sub>	Don't Care	-5	85	mA
		-6	75	mA
		-7	65	mA
I <sub>CC2</sub>	Don't Care	Don't Care	2	mA
I <sub>CC3</sub>	Don't Care	-5	85	mA
		-6	75	mA
		-7	65	mA
I <sub>CC4</sub>	Don't Care	-5	85	mA
		-6	75	mA
		-7	6	mA
I <sub>CC5</sub>	Normal L	Don't Care	1	mA
			200	uA
I <sub>CC6</sub>	Don't Care	-5	85	mA
		-6	75	mA
		-7	65	mA

I<sub>CC1</sub>\* : Operating Current ( $\overline{RAS}$  and  $\overline{CAS}$  cycling @t<sub>RC</sub>=min.)

I<sub>CC2</sub> : Standby Current ( $\overline{RAS}=\overline{CAS}=\overline{W}=V_{IH}$ )

I<sub>CC3</sub>\* :  $\overline{RAS}$ -only Refresh Current ( $\overline{CAS}=V_{IH}$ ,  $\overline{RAS}$ , Address cycling @t<sub>RC</sub>=min.)

I<sub>CC4</sub>\* : EDO Mode Current ( $\overline{RAS}=V_{IL}$ ,  $\overline{CAS}$ , Address cycling @t<sub>HPC</sub>=min.)

I<sub>CC5</sub> : Standby Current ( $\overline{RAS}=\overline{CAS}=\overline{W}=V_{CC}-0.2V$ )

I<sub>CC6</sub>\* :  $\overline{CAS}$ -Before- $\overline{RAS}$  Refresh Current ( $\overline{RAS}$  and  $\overline{CAS}$  cycling @t<sub>RC</sub>=min)

**\*Note** : I<sub>CC1</sub>, I<sub>CC3</sub>, I<sub>CC4</sub> and I<sub>CC6</sub> are dependent on output loading and cycle rates. Specified values are obtained with the output open. I<sub>CC</sub> is specified as an average current. In I<sub>CC1</sub>, I<sub>CC3</sub> and I<sub>CC6</sub> address can be changed maximum once while  $\overline{RAS}=V_{IL}$ . In I<sub>CC4</sub>, address can be changed maximum once within one hyper page cycle time, t<sub>HPC</sub>.

## CAPACITANCE (TA=25°C, VCC=5V, f=1MHz)

Parameter	Symbol	Min	Max	Units
Input capacitance [A0 ~ A9]	CIN1	-	5	pF
Input capacitance [ $\overline{\text{RAS}}$ , $\overline{\text{CAS}}$ , $\overline{\text{W}}$ , $\overline{\text{OE}}$ ]	CIN2	-	7	pF
Output capacitance [DQ0 - DQ3]	CDQ	-	7	pF

## AC CHARACTERISTICS (0°C ≤ TA ≤ 70°C, See note 1,2)

Test condition : VCC=5.0V±10%, Vih/Vil=2.4/0.8V, Voh/Vol=2.0/0.8V

Parameter	Symbol	-5		-6		7		Units	Notes
		Min	Max	Min	Max	Min	Max		
Random read or write cycle time	tRC	84		104		124		ns	
Read-modify-write cycle time	tRWC	116		138		163		ns	
Access time from $\overline{\text{RAS}}$	tRAC		50		60		70	ns	3,4,10
Access time from $\overline{\text{CAS}}$	tCAC		15		15		20	ns	3,4,5,22
Access time from column address	tAA		25		30		35	ns	3,10
$\overline{\text{CAS}}$ to output in Low-Z	tCLZ	3		3		3		ns	3,22
Output buffer turn-off delay from $\overline{\text{CAS}}$	tCEZ	3	13	3	13	3	18	ns	6,13,22
Transition time (rise and fall)	tT	2	50	2	50	2	50	ns	2
$\overline{\text{RAS}}$ precharge time	tRP	30		40		50		ns	
$\overline{\text{RAS}}$ pulse width	tRAS	50	10K	60	10K	70	10K	ns	
$\overline{\text{RAS}}$ hold time	tRSH	15		15		20		ns	18
$\overline{\text{CAS}}$ hold time	tCSH	40		50		60		ns	21
$\overline{\text{CAS}}$ pulse width	tCAS	8	10K	10	10K	15	10K	ns	27
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ delay time	tRCD	20	35	20	45	20	50	ns	4,20
$\overline{\text{RAS}}$ to column address delay time	tRAD	15	25	15	30	15	35	ns	10
$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ precharge time	tCRP	5		5		5		ns	19
Row address set-up time	tASR	0		0		0		ns	
Row address hold time	tRAH	10		10		10		ns	
Column address set-up time	tASC	0		0		0		ns	20
Column address hold time	tCAH	8		10		15		ns	20
Column address to $\overline{\text{RAS}}$ lead time	tRAL	25		30		35		ns	
Read command set-up time	tRCS	0		0		0		ns	
Read command hold time referenced to $\overline{\text{CAS}}$	tRCH	0		0		0		ns	8
Read command hold time referenced to $\overline{\text{RAS}}$	tRRH	0		0		0		ns	8
Write command hold time	tWCH	10		10		15		ns	28
Write command pulse width	tWP	10		10		15		ns	
Write command to $\overline{\text{RAS}}$ lead time	tRWL	15		15		15		ns	
Write command to $\overline{\text{CAS}}$ lead time	tCWL	8		10		15		ns	21
Data set-up time	tDS	0		0		0		ns	9
Data hold time	tDH	8		10		15		ns	9

**AC CHARACTERISTICS** (Continued)

Parameter	Symbol	-5		-6		-7		Units	Notes
		Min	Max	Min	Max	Min	Max		
Refresh period (4K, Normal)	tREF		16		16		16	ms	
Refresh period (L-ver)	tREF		128		128		128	ms	
Write command set-up time	twCS	0		0		0		ns	7,20
CAS to $\overline{W}$ delay time	tcWD	32		32		42		ns	7,20
RAS to $\overline{W}$ delay time	trWD	67		77		92		ns	7
Column address to $\overline{W}$ delay time	tAWD	42		47		57		ns	7
CAS precharge to $\overline{W}$ delay time	tcPWD	45		52		62		ns	7
CAS set-up time (CAS -before-RAS refresh)	tCSR	5		5		5		ns	20
CAS hold time (CAS -before-RAS refresh)	tCHR	10		10		15		ns	19
RAS to CAS precharge time	trPC	5		5		5		ns	
CAS precharge time (C-B-R counter test cycle)	tcPT	20		20		25		ns	
Access time from CAS precharge	tcPA		28		35		40	ns	3,20
Hyper Page mode cycle time	tHPC	20		25		30		ns	15,23
Hyper Page read-modify-write cycle time	tHPRWC	57		66		81		ns	23
CAS precharge time (Hyper Page cycle)	tcp	8		10		10		ns	24
RAS pulse width (Hyper Page cycle)	trASP	50	200K	60	200K	70	200K	ns	
RAS hold time from CAS precharge	trHCP	30		35		40		ns	
OE access time	toEA		15		15		20	ns	25
OE to data delay	toED	13		13		18		ns	25
Output buffer turn off delay time from OE	toEZ	3	13	3	13	3	18	ns	6,13
OE to output in low-Z	tolZ	3		3		3			
OE command hold time	toEH	15		15		20		ns	
Output data hold time	tDOH	5		5		5		ns	
Output buffer turn off delay time from RAS	treZ	3	15	3	15	3	20	ns	6,13
Output buffer turn off delay time from $\overline{W}$	twez	3	13	3	13	3	18	ns	6,13
$\overline{W}$ to data delay	twED	13		13		18		ns	
OE to CAS hold time	toCH	5		5		5		ns	
CAS hold time to OE	tCHO	5		5		5		ns	
OE precharge time	toEP	5		5		5		ns	
$\overline{W}$ pulse width (hyper page cycle)	twPE	5		5		5		ns	
Write command set-up time (Test mode in)	twTS	10		10		10		ns	
Write command hold time (Test mode in)	twTH	10		10		10		ns	
$\overline{W}$ to RAS precharge time (C-B-R refresh)	twRP	10		10		10		ns	
$\overline{W}$ to RAS hold time (C-B-R refresh)	twRH	10		10		10		ns	
Hold time CAS low to CAS high	tCLCH	5		5		5		ns	16,28

## TEST MODE CYCLE

( Note 11 )

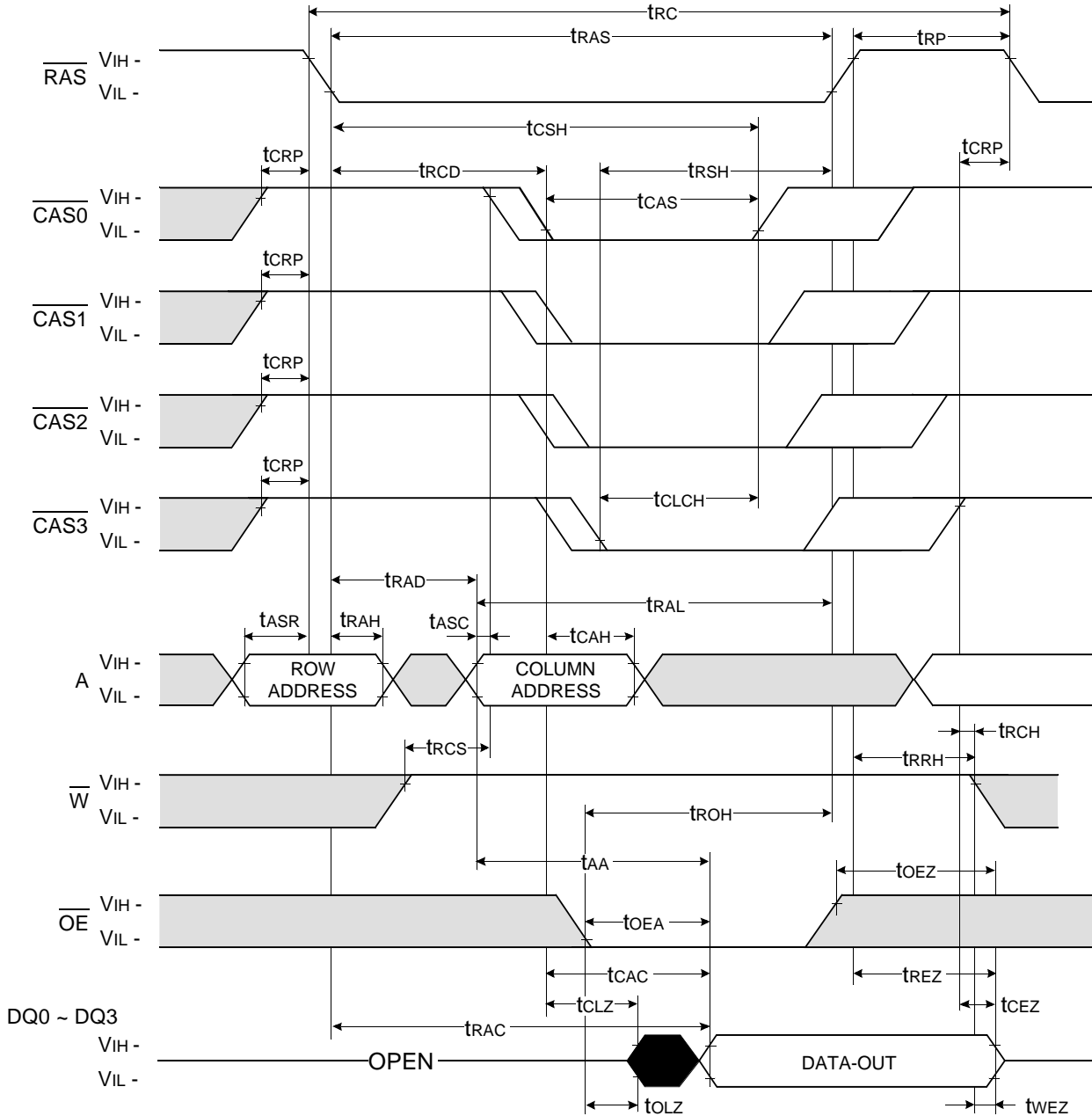
Parameter	Symbol	-5		-6		-7		Units	Notes
		Min	Max	Min	Max	Min	Max		
Random read or write cycle time	t <sub>RC</sub>	89		109		129		ns	
Read-modify-write cycle time	t <sub>RWC</sub>	121		145		170		ns	
Access time from $\overline{\text{RAS}}$	t <sub>RAC</sub>		55		65		75	ns	3,4,10,12
Access time from $\overline{\text{CAS}}$	t <sub>CAC</sub>		18		20		25	ns	3,4,5,12
Access time from column address	t <sub>AA</sub>		30		35		40	ns	3,10,12
$\overline{\text{RAS}}$ pulse width	t <sub>RAS</sub>	55	10K	65	10K	75	10K	ns	
$\overline{\text{CAS}}$ pulse width	t <sub>CAS</sub>	13	10K	15	10K	20	10K	ns	
$\overline{\text{RAS}}$ hold time	t <sub>RS</sub>	18		20		25		ns	
$\overline{\text{CAS}}$ hold time	t <sub>CS</sub>	45		55		65		ns	
Column Address to $\overline{\text{RAS}}$ lead time	t <sub>RAL</sub>	30		35		40		ns	
$\overline{\text{CAS}}$ to $\overline{\text{W}}$ delay time	t <sub>CWD</sub>	35		39		49		ns	7
$\overline{\text{RAS}}$ to $\overline{\text{W}}$ delay time	t <sub>RWD</sub>	72		84		94		ns	7
Column Address to $\overline{\text{W}}$ delay time	t <sub>AWD</sub>	47		54		64		ns	7
Hyper Page mode cycle time	t <sub>HPC</sub>	25		30		35		ns	
Hyper Page mode read-modify-write cycle	t <sub>HPRWC</sub>	52		61		76		ns	
$\overline{\text{RAS}}$ pulse width (Fast Page cycle)	t <sub>RASP</sub>	55	200K	65	200K	75	200K	ns	
Access time from $\overline{\text{CAS}}$ precharge	t <sub>CPA</sub>		33		40		45	ns	3
$\overline{\text{OE}}$ access time	t <sub>OEA</sub>		18		20		25	ns	
$\overline{\text{OE}}$ to data delay	t <sub>OED</sub>	18		20		25		ns	
$\overline{\text{OE}}$ command hold time	t <sub>OEH</sub>	18		20		25		ns	

## NOTES

1. An initial pause of 200us is required after power-up followed by any 8  $\overline{\text{RAS}}$ -only refresh or  $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  refresh cycles before proper device operation is achieved.
2.  $V_{IH}(\text{min})$  and  $V_{IL}(\text{max})$  are reference levels for measuring timing of input signals.  
Transition times are measured between  $V_{IH}(\text{min})$  and  $V_{IL}(\text{max})$  and are assumed to be 2ns for all inputs.
3. Measured with a load equivalent to 2 TTL load and 100pF.
4. Operation within the  $t_{\text{RCD}}(\text{max})$  limit insures that  $t_{\text{RAC}}(\text{max})$  can be met.  $t_{\text{RCD}}(\text{max})$  is specified as a reference point only.  
If  $t_{\text{RCD}}$  is greater than the specified  $t_{\text{RCD}}(\text{max})$  limit, then access time is controlled exclusively by  $t_{\text{CAC}}$ .
5. Assumes that  $t_{\text{RCD}} \geq t_{\text{RCD}}(\text{max})$ .
6. This parameter defines the time at which the output achieves the open circuit condition and is not referenced to  $V_{OH}$  or  $V_{OL}$ .
7.  $t_{\text{WCS}}$ ,  $t_{\text{RWD}}$ ,  $t_{\text{CWD}}$ ,  $t_{\text{AWD}}$  and  $t_{\text{CPWD}}$  are non restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If  $t_{\text{WCS}} \geq t_{\text{WCS}}(\text{min})$ , the cycle is an early write cycle and the data output will remain high impedance for the duration of the cycle. If  $t_{\text{CWD}} \geq t_{\text{CWD}}(\text{min})$ ,  $t_{\text{RWD}} \geq t_{\text{RWD}}(\text{min})$ ,  $t_{\text{AWD}} \geq t_{\text{AWD}}(\text{min})$  and  $t_{\text{CPWD}} \geq t_{\text{CPWD}}(\text{min})$  then the cycle is a read-modify-write cycle and the data output will contain the data read from the selected address. If neither of the above conditions is satisfied, the condition of the data out is indeterminate.
8. Either  $t_{\text{RCH}}$  or  $t_{\text{RRH}}$  must be satisfied for a read cycle.
9. These parameters are referenced to the first  $\overline{\text{CAS}}$  falling edge in early write cycles and to  $\overline{\text{W}}$  falling edge in  $\overline{\text{OE}}$  controlled write cycle and read-modify-write cycles.
10. Operation within the  $t_{\text{RAD}}(\text{max})$  limit insures that  $t_{\text{RAC}}(\text{max})$  can be met.  $t_{\text{RAD}}(\text{max})$  is specified as a reference point only.  
If  $t_{\text{RAD}}$  is greater than the specified  $t_{\text{RAD}}(\text{max})$  limit, then access time is controlled by  $t_{\text{AA}}$ .
11. These specifications are applied in the test mode.
12. In test mode read cycle, the value of  $t_{\text{RAC}}$ ,  $t_{\text{AA}}$ ,  $t_{\text{CAC}}$  is delayed by 2ns to 5ns for the specified values. These parameters should be specified in test mode cycles by adding the above value to the specified value in this data sheet.
13.  $t_{\text{CEZ}}(\text{MAX})$ ,  $t_{\text{TREZ}}(\text{MAX})$ ,  $t_{\text{TOEZ}}(\text{MAX})$  and  $t_{\text{TWEZ}}(\text{MAX})$  define the time at which the output achieves the open circuit condition and are not referenced to output voltage level.
14. If  $\overline{\text{RAS}}$  goes high before  $\overline{\text{CAS}}$  high going, the open circuit condition of the output is achieved by  $\overline{\text{CAS}}$  high going.  
If  $\overline{\text{CAS}}$  goes high before  $\overline{\text{RAS}}$  high going, the open circuit condition of the output is achieved by  $\overline{\text{RAS}}$  high going.
15.  $t_{\text{ASC}} \geq 6.0\text{ns}$ , Assumes  $t_{\text{T}} = 2.0\text{ns}$
16. In order to hold the address latched by the first  $\overline{\text{CASx}}$  going low, the parameter  $t_{\text{CLCH}}$  must be met.
17. If at least one  $\overline{\text{CAS}}$  is low at the falling edge of  $\overline{\text{RAS}}$ , DQ will be maintained from the previous cycle.  
To initiate a new cycle and clear the data out buffer, all four  $\overline{\text{CAS}}$  must be pulsed high for  $t_{\text{CP}}$ .
18. The last  $\overline{\text{CASx}}$  edge to go low.
19. The last  $\overline{\text{CASx}}$  edge to go high.
20. The first  $\overline{\text{CASx}}$  edge to go low.
21. The first  $\overline{\text{CASx}}$  edge to go high.
22. Output parameter is referenced to corresponding  $\overline{\text{CASx}}$  Input.
23. The last rising  $\overline{\text{CASx}}$  edge to next cycle's last rising  $\overline{\text{CASx}}$  edge.
24. The last rising  $\overline{\text{CASx}}$  edge to first falling  $\overline{\text{CASx}}$  edge.
25. The first DQx controlled by the first  $\overline{\text{CASx}}$  to go low.
26. The last DQx controlled by the first  $\overline{\text{CASx}}$  to go high.
27. Each  $\overline{\text{CASx}}$  must meet minimum pulse width.
28. The last falling  $\overline{\text{CASx}}$  edge to the first rising  $\overline{\text{CASx}}$  edge.



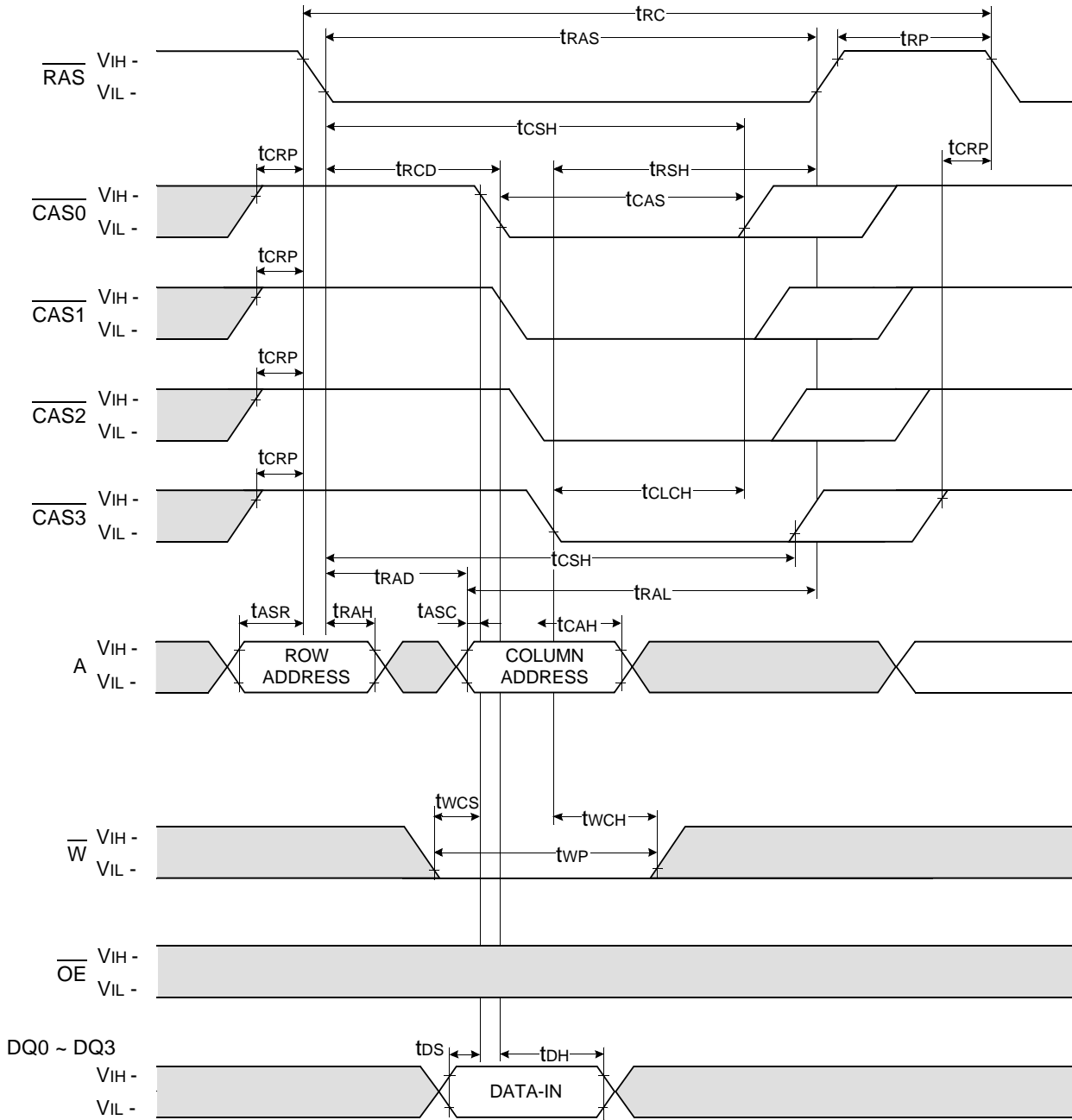
READ CYCLE



Don't care  
 Undefined

WRITE CYCLE ( EARLY WRITE )

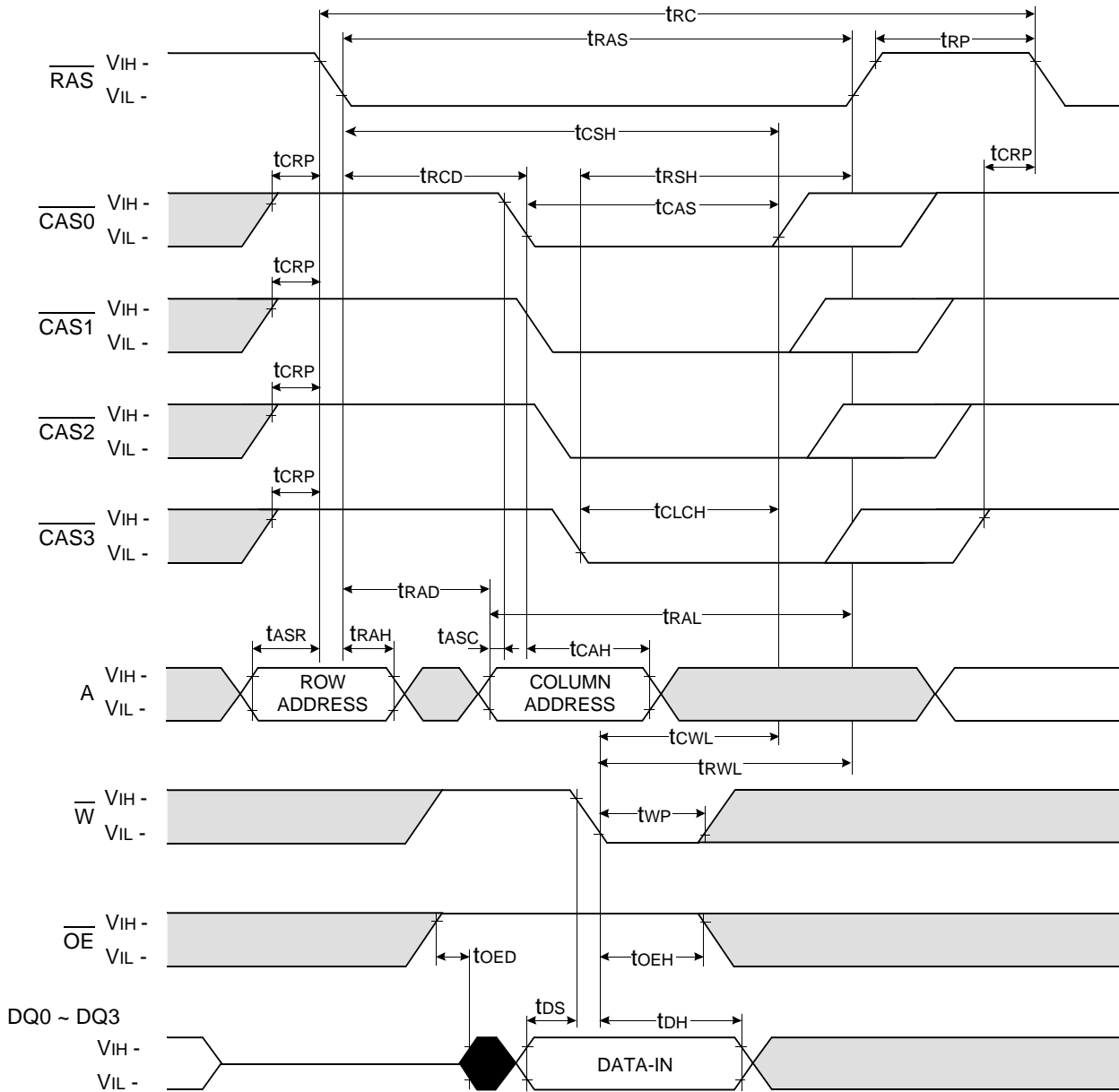
NOTE : DOUT = OPEN



Don't care  
 Undefined

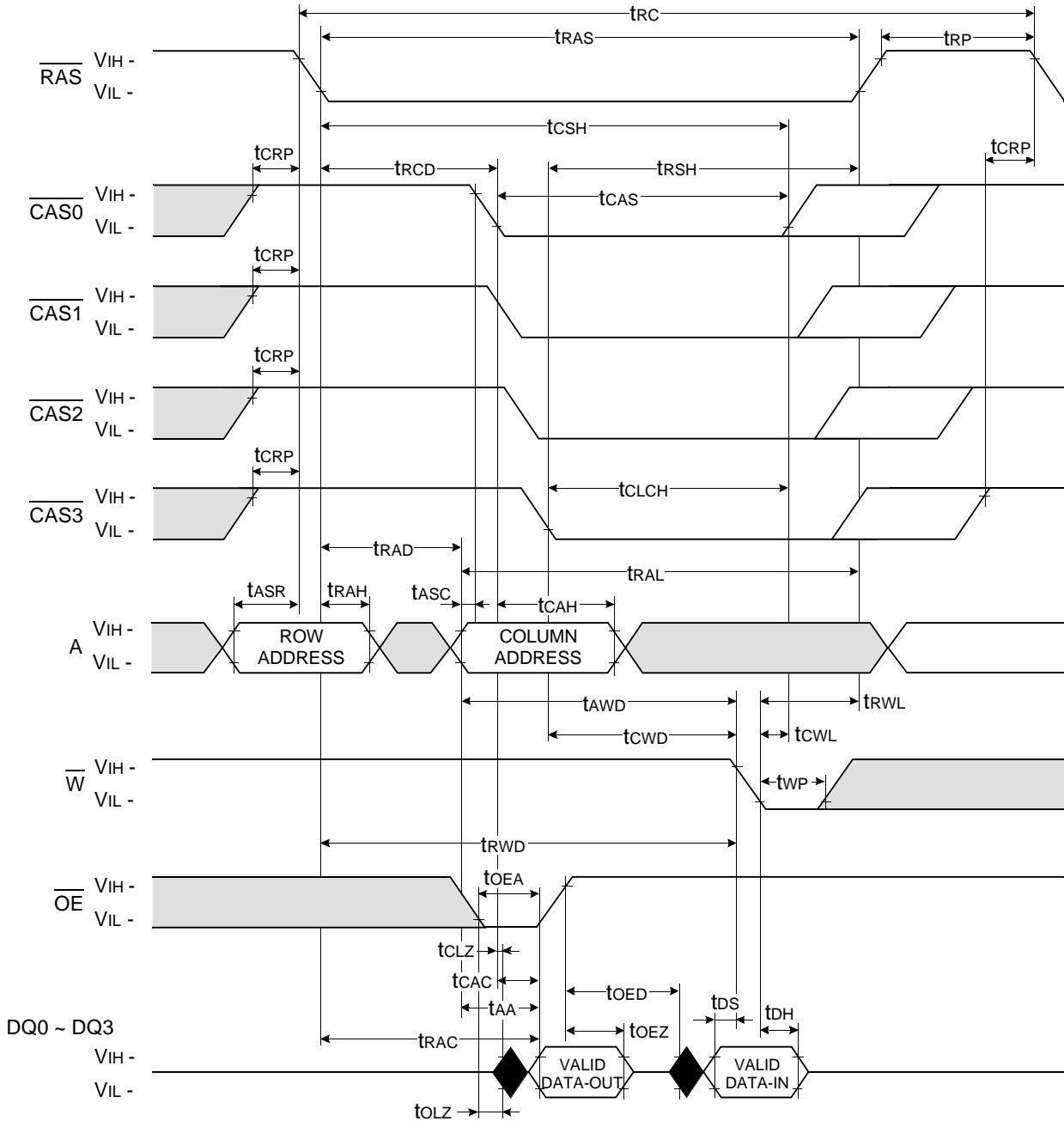
WRITE CYCLE (  $\overline{\text{OE}}$  CONTROLLED WRITE )

NOTE : DOUT = OPEN



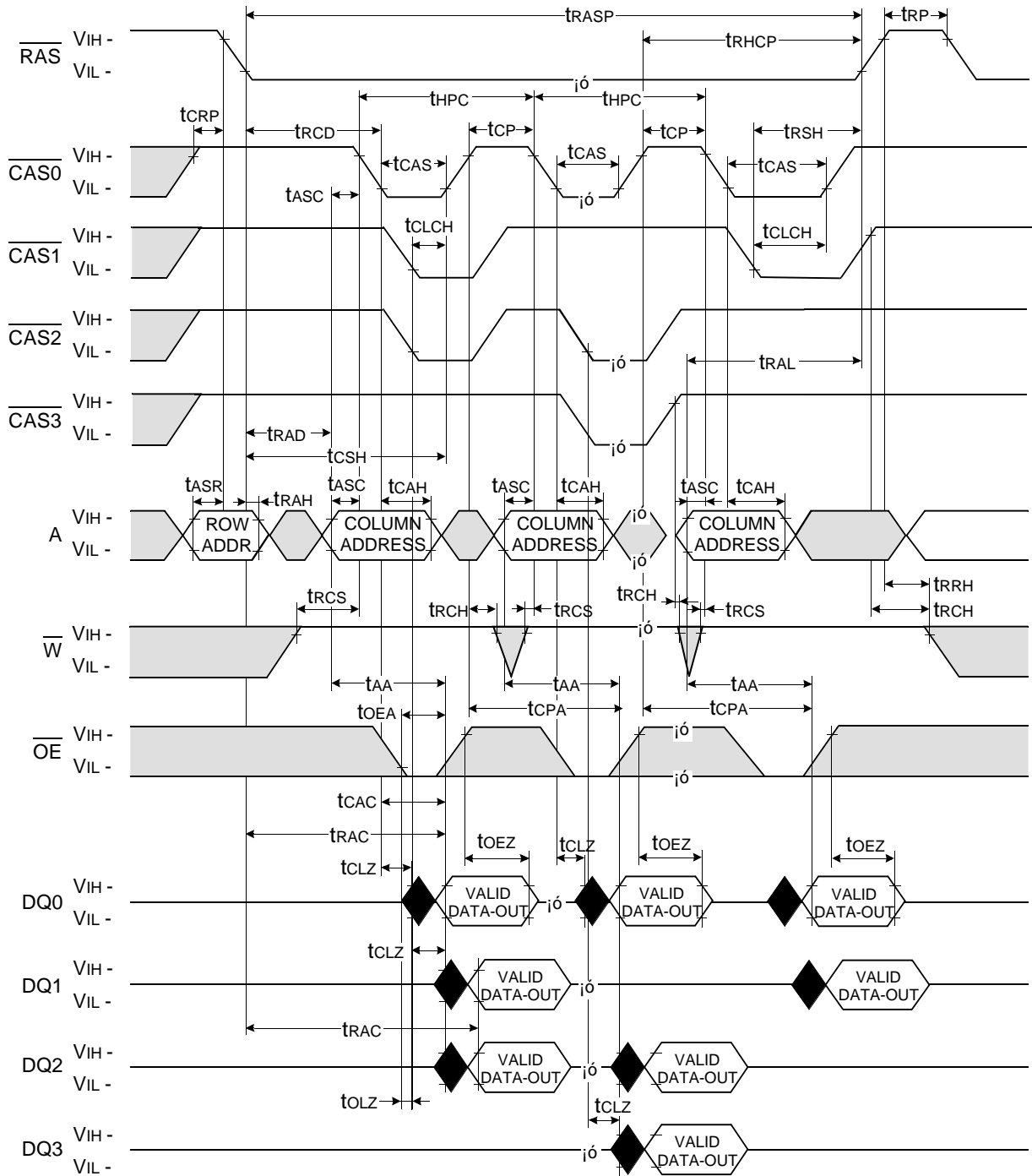
Don't care  
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READ - MODIFY - WRITE CYCLE



Don't care  
 Undefined

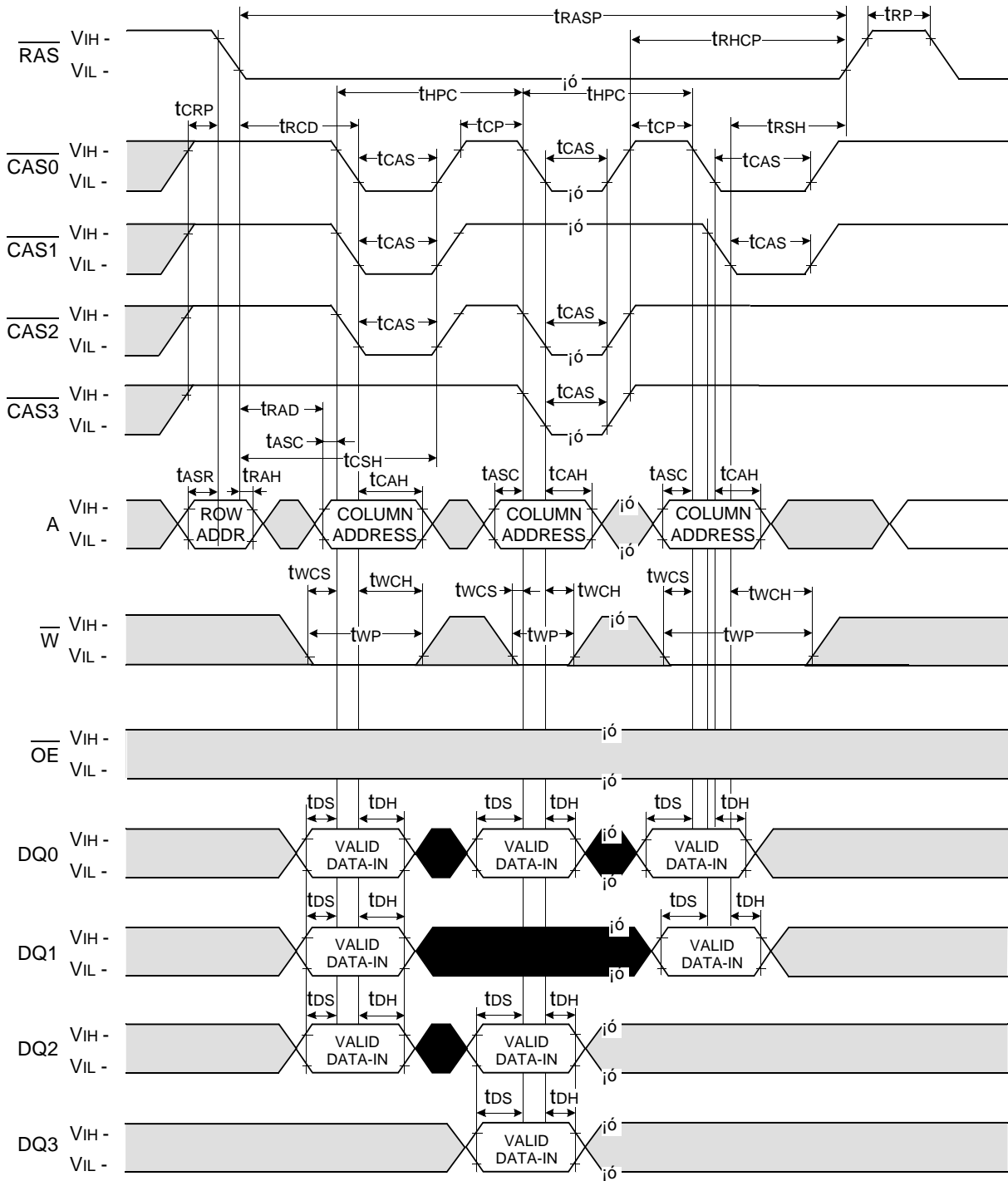
HYPER PAGE MODE READ CYCLE



Don't care  
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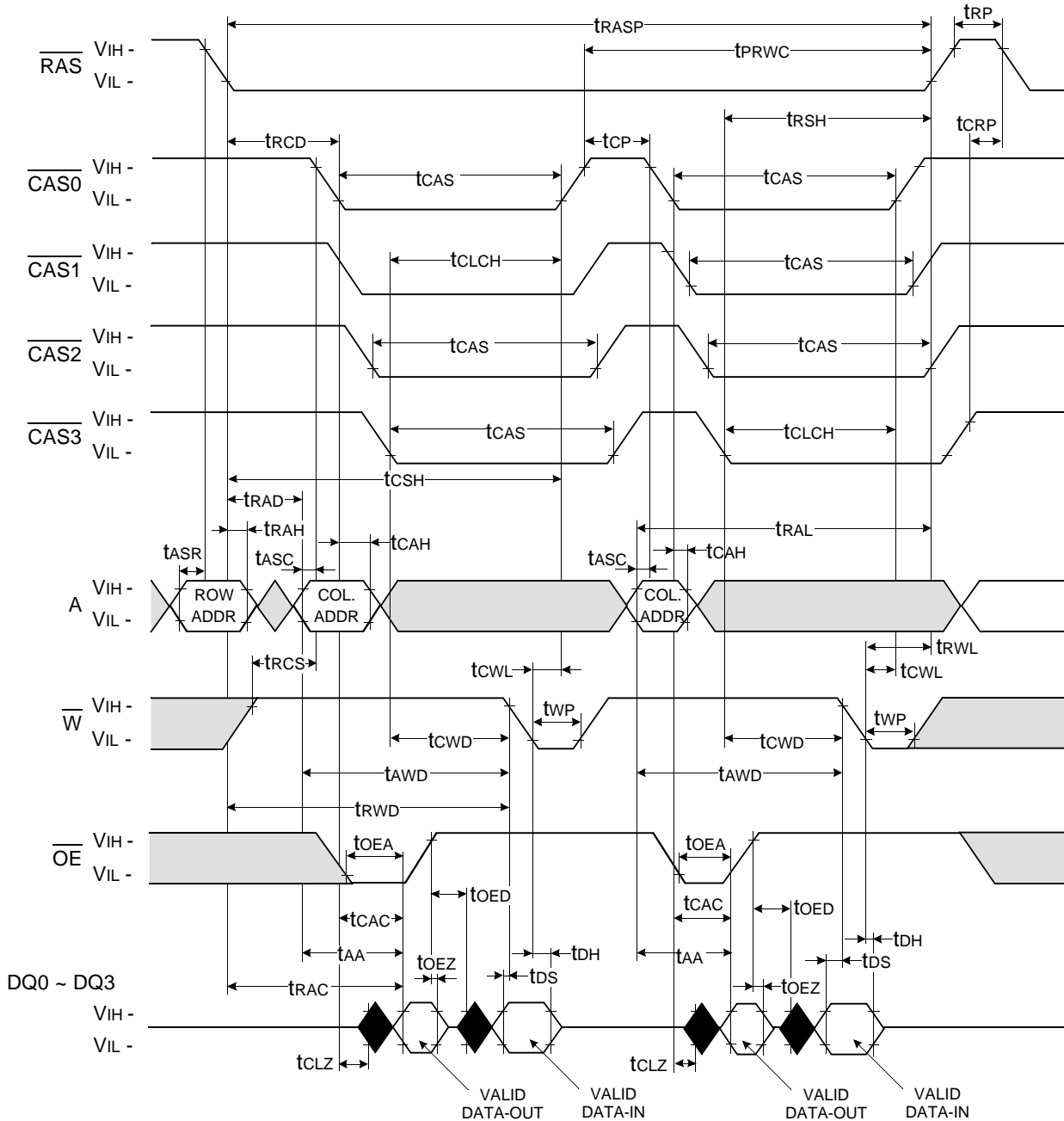
HYPER PAGE MODE WRITE CYCLE ( EARLY WRITE )

NOTE : DOUT = OPEN



Don't care  
 Undefined

HYPER PAGE READ - MODIFY - WRITE CYCLE

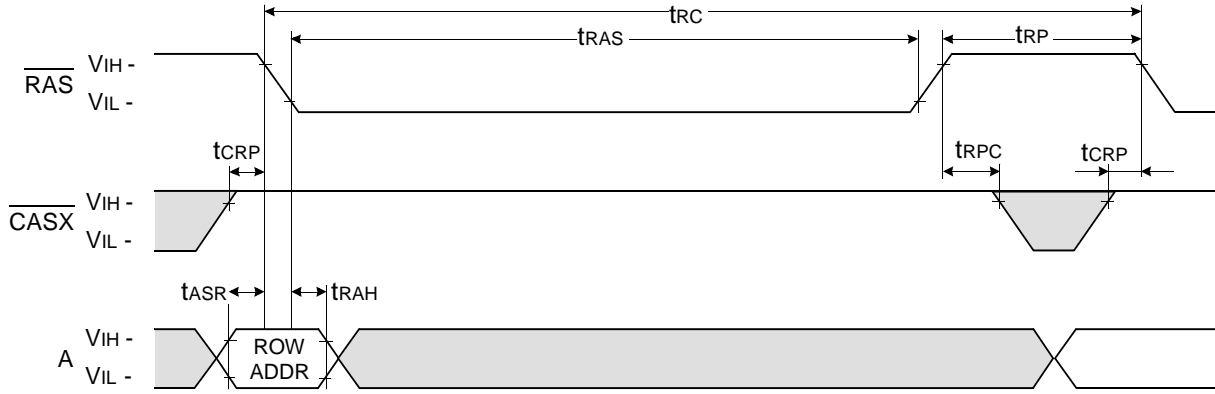


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**$\overline{\text{RAS}}$  - ONLY REFRESH CYCLE\***

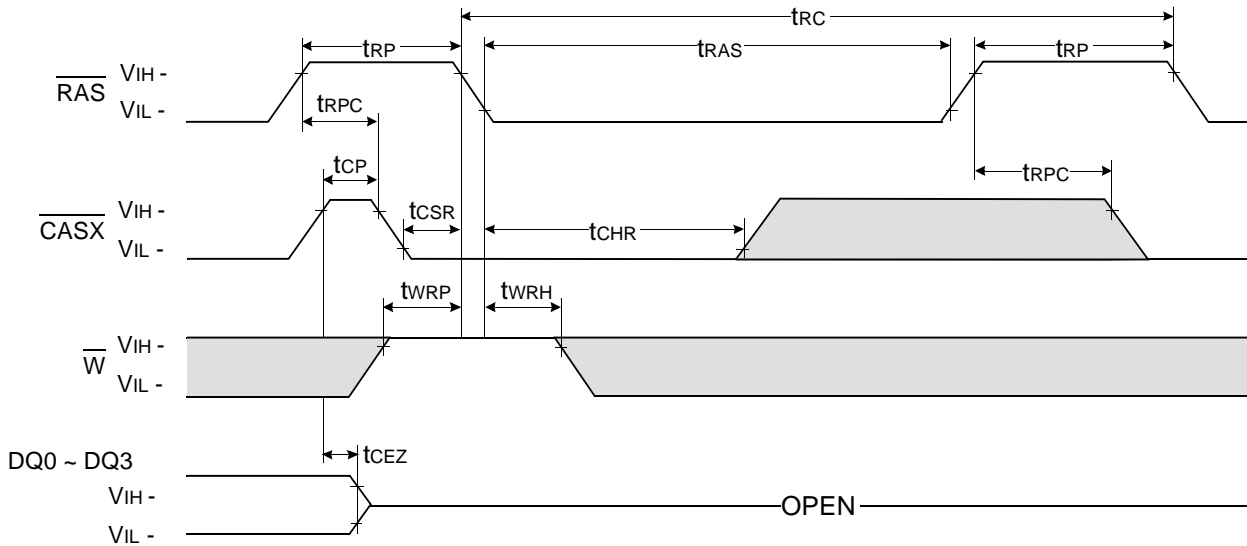
NOTE :  $\overline{\text{W}}$ ,  $\overline{\text{OE}}$ ,  $\text{DIN}$  = Don't care

$\text{DOUT}$  = OPEN



**$\overline{\text{CAS}}$  - BEFORE -  $\overline{\text{RAS}}$  REFRESH CYCLE**

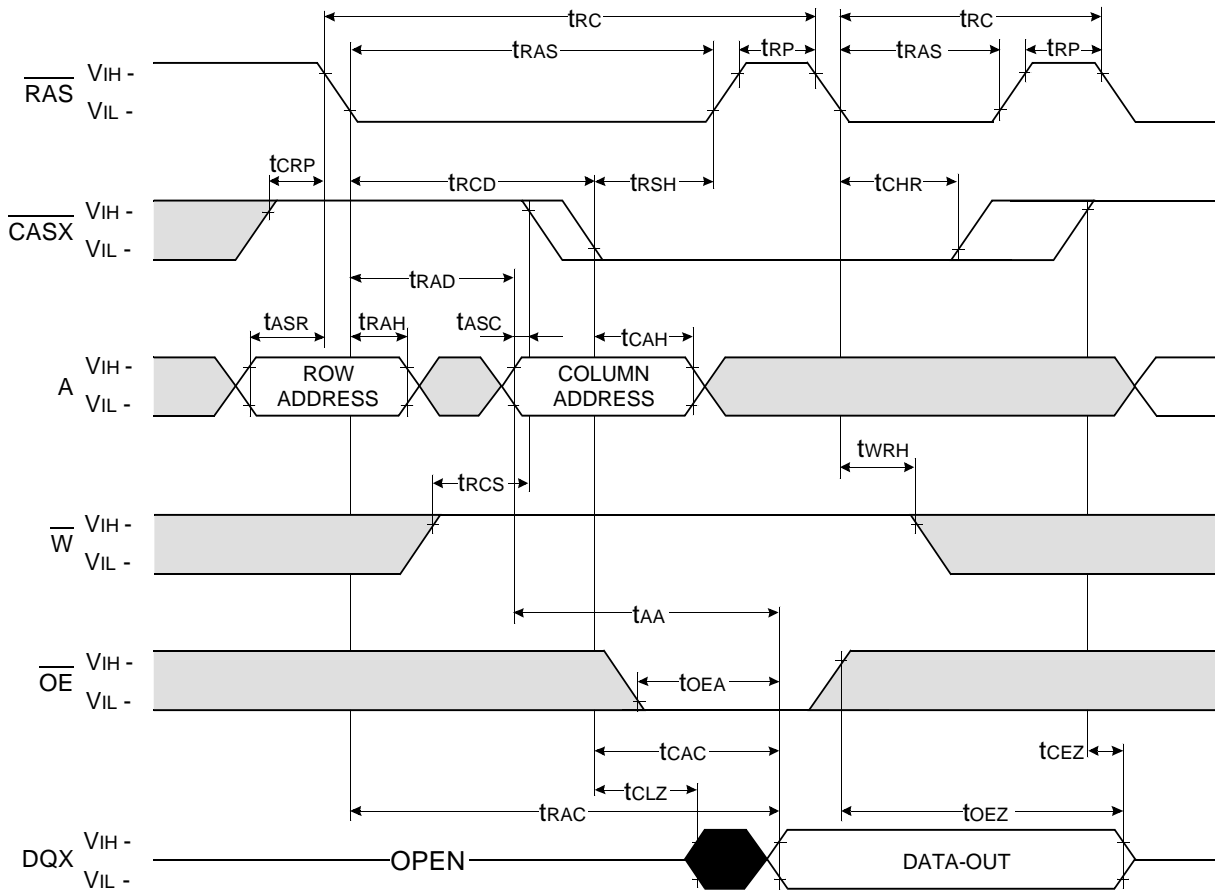
NOTE :  $\overline{\text{OE}}$ ,  $\text{A}$  = Don't care



Don't care  
 Undefined



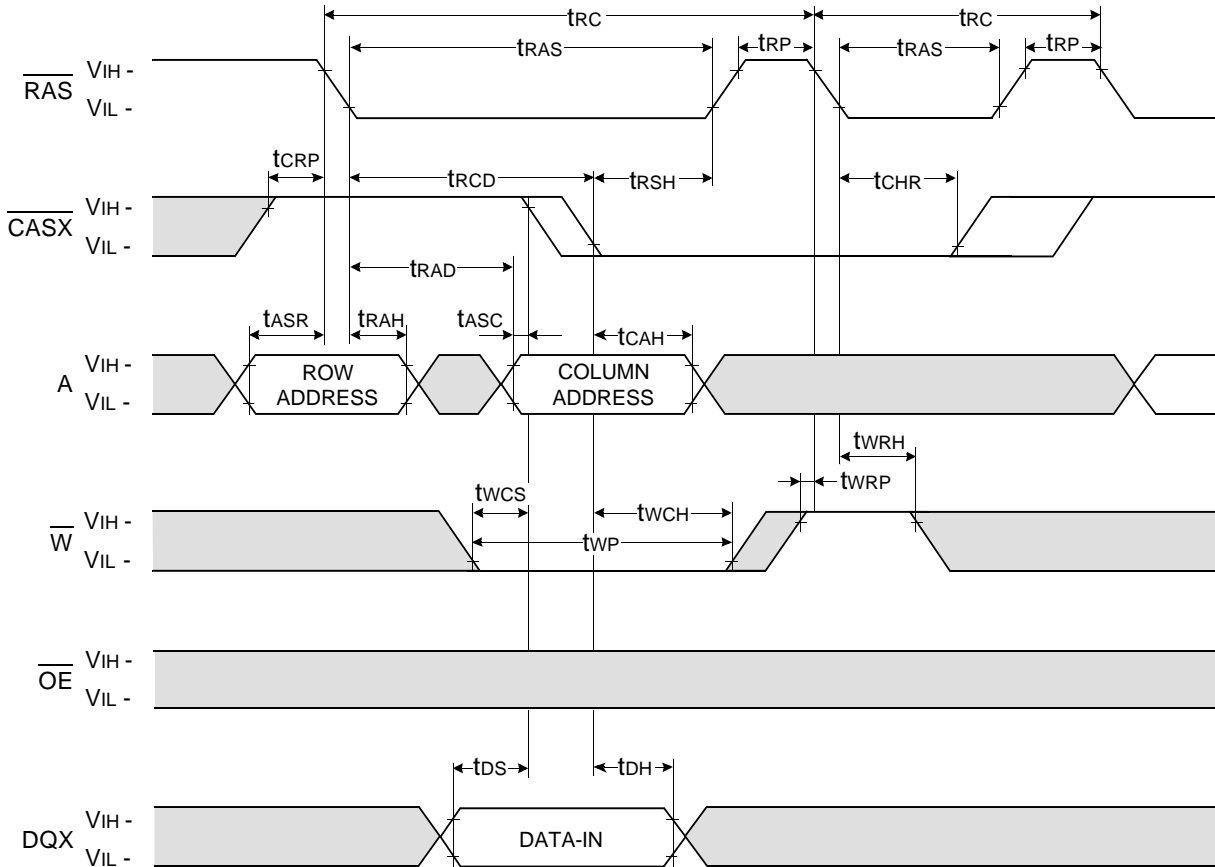
HIDDEN REFRESH CYCLE ( READ )



Don't care  
 Undefined

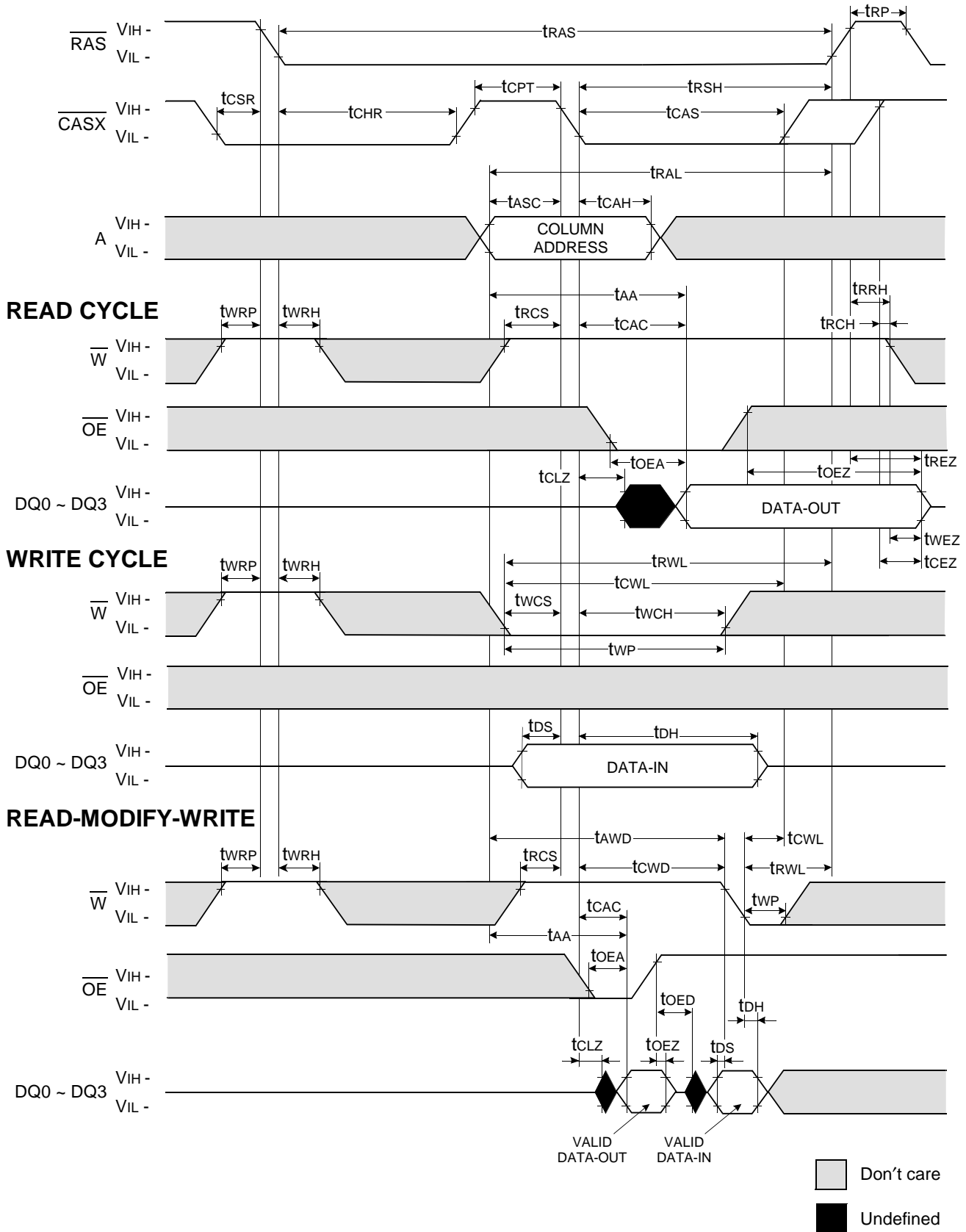
**HIDDEN REFRESH CYCLE ( WRITE )**

NOTE : DOUT = OPEN



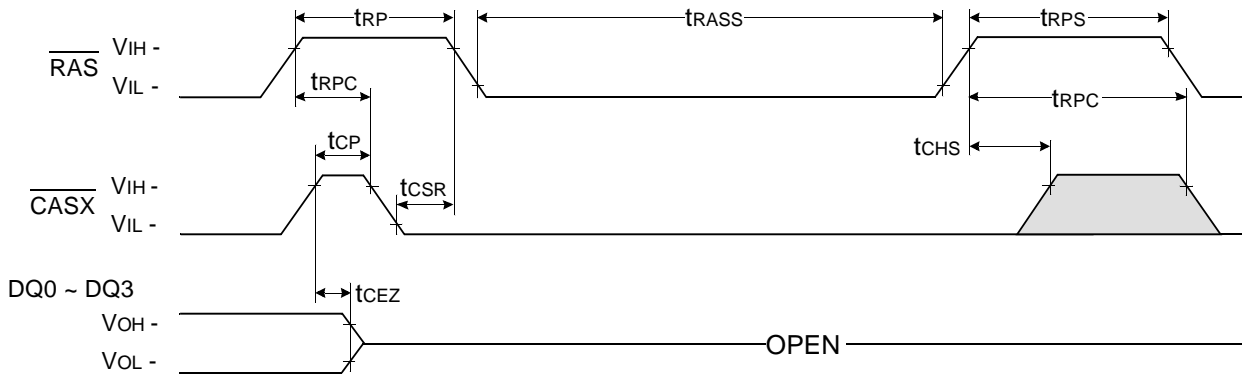
Don't care  
 Undefined

**CAS-BEFORE-RAS REFRESH CYCLE TEST CYCLE**



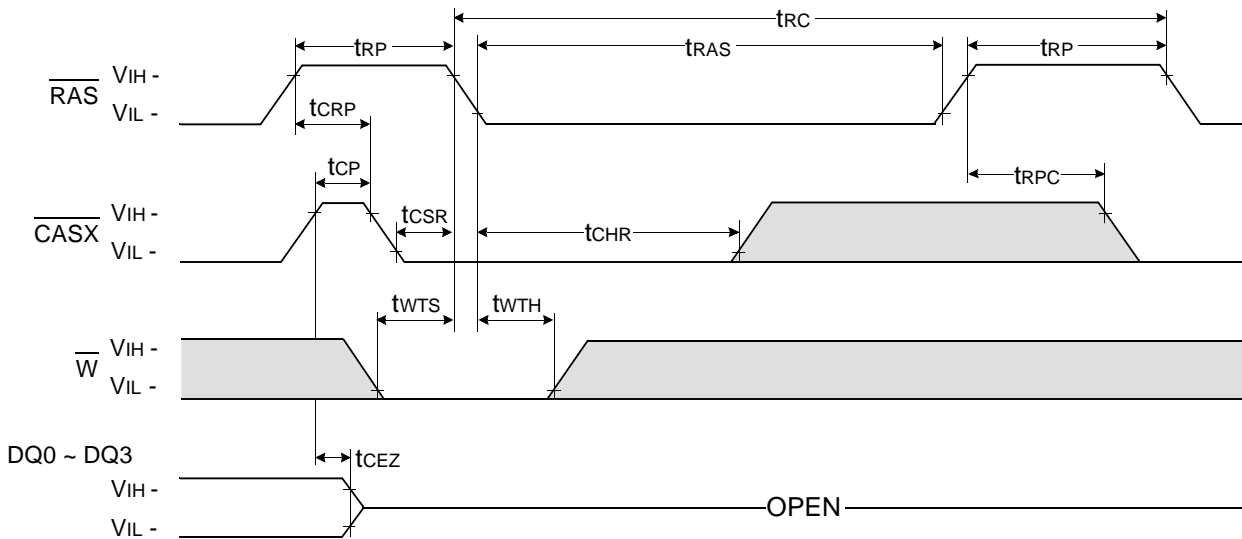
**CAS - BEFORE - RAS SELF REFRESH CYCLE**

NOTE :  $\overline{OE}$ , A = Don't care,  $\overline{WE} = V_{cc} - 0.2V$



**TEST MODE IN CYCLE**

NOTE :  $\overline{OE}$ , A = Don't care



Don't care  
 Undefined

PACKAGE DIMENSION

